GT PSLM31.13

DURIS® S 5

The compact, mid-power Duris® S 5 LED with industry standard 3030 package that comes with high efficacy, color quality and long lifetime. Ideal choice for indoor General Lighting applications.





Applications

- Architecture
- Architecture / Garden Lighting (LED & Laser)
- Medical Illumination

- Mood Lighting
- Photo Therapy

Features:

- Package: white SMT package, colorless clear resin
- Typ. Radiation: 120° (Lambertian emitter)
- Lumen maintenance: LM-80-15 in progress
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- Luminous Flux: typ. 36.6 lm
- Luminous efficacy: typ. 135 lm/W



Ordering Information

Туре	Luminous Flux ¹⁾ I _F = 100 mA Φ_V	Ordering Code	
GT PSLM31.13-HRHT-26-KM	33.0 41.9 lm	Q65112A6165	



Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T _{op}	min.	-40 °C
	θþ	max.	100 °C
Storage Temperature	T _{stg}	min.	-40 °C
	5.9	max.	100 °C
Junction Temperature	Tj	max.	125 °C
Forward current	I _F	min.	10 mA
	·	max.	200 mA
Surge Current	I _{FS}	max.	300 mA
t \leq 10 µs; D = 0.005 ; T _J = 25 °C	10		
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV



Characteristics

I_F = 100 mA; T_J = 25 °C

Parameter	Symbol		Values
Dominant Wavelength ²⁾ I _F = 100 mA	λ_{dom}	min. typ. max.	513 nm 528 nm 543 nm
Viewing angle at 50% I_v	2φ	typ.	120 °
Forward Voltage ³⁾ I _F = 100 mA	V _F	min. typ. max.	2.60 V 2.70 V 3.20 V
Electrical thermal resistance junction/solderpoint with efficiency η_e = 17.4 %	$R_{thJSelec.}$	typ.	18 K / W



Brightness Groups

Group	Luminous Flux ¹⁾ I _F = 100 mA min. Φ_v	Luminous Flux ¹⁾ I _F = 100 mA max. Φ_v	
HR	33.0 lm	35.9 lm	
HS	35.9 lm	39.0 lm	
HT	39.0 lm	41.9 lm	

Forward Voltage Groups

Group	Forward Voltage ³⁾ I _F = 100 mA min. V _F	Forward Voltage ³⁾ I _F = 100 mA max. V _F	
K	2.60 V	2.80 V	
L	2.80 V	3.00 V	
Μ	3.00 V	3.20 V	

Wavelength Groups

Group	Dominant Wavelength ²⁾ $I_F = 100 \text{ mA}$ min. λ_{dom}	Dominant Wavelength ²⁾ I _F = 100 mA max. λ_{dom}	
2	513 nm	519 nm	
3	519 nm	525 nm	
4	525 nm	531 nm	
5	531 nm	537 nm	
6	537 nm	543 nm	



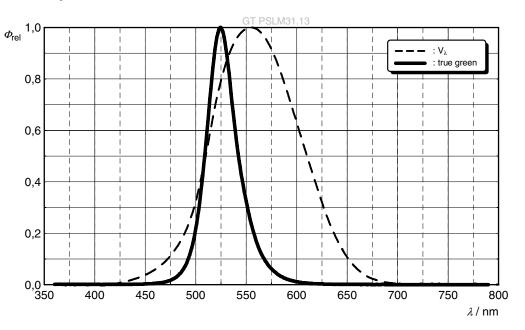
Group Name on Label

Example: HR-2-K Brightness	Wavelength	Forward Voltage
HR	2	К



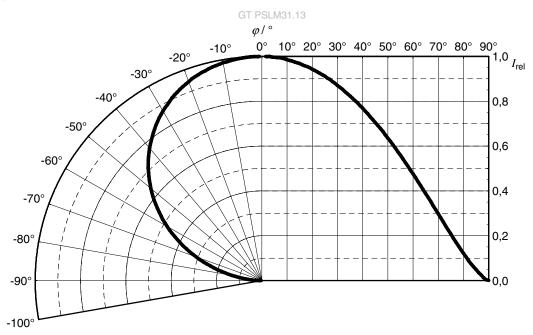
Relative Spectral Emission⁴⁾

 $\Phi_{_{rel}}$ = f (λ); I_F = 100 mA; T_J = 25 °C



Radiation Characteristics⁴⁾

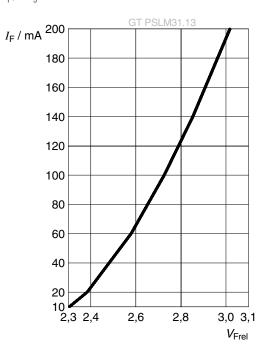
 $I_{rel} = f(\phi); T_J = 25 \ ^{\circ}C$





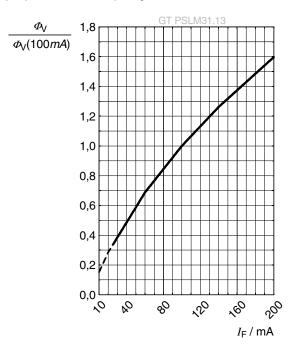
Forward current ^{4), 5)}

 $I_F = f(V_F); T_J = 25 \ ^{\circ}C$



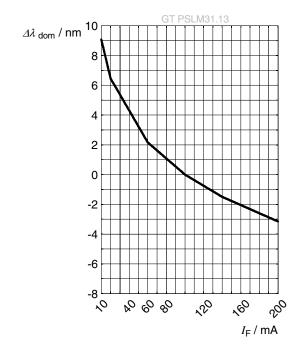
Relative Luminous Flux^{4), 5)}

 $\Phi_v/\Phi_v(100 \text{ mA}) = f(I_F); T_J = 25 \text{ °C}$

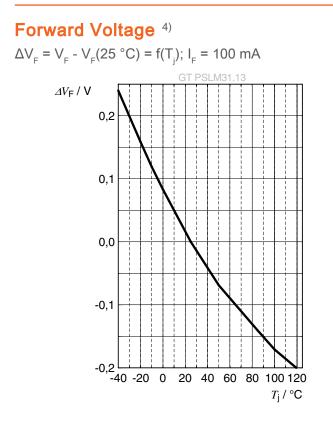


Dominant Wavelength⁴⁾

 $\Delta \lambda_{dom} = f(I_F); T_J = 25 \ ^{\circ}C$

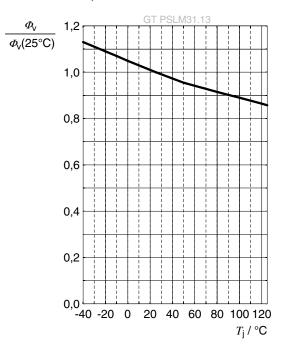






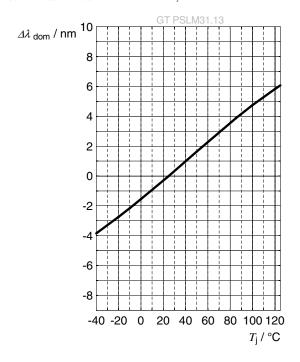
Relative Luminous Flux⁴⁾

 $\Phi_v/\Phi_v(25 \text{ °C}) = f(T_i); I_F = 100 \text{ mA}$



Dominant Wavelength ⁴⁾

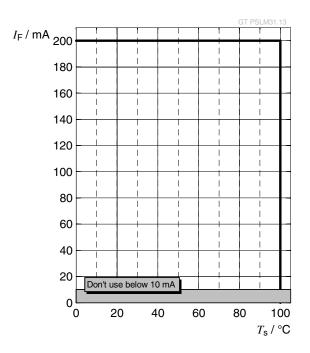
 $\Delta \lambda_{dom} = \lambda_{dom} - \lambda_{dom} (25 \ ^{\circ}C) = f(T_{j}); \ I_{_{F}} = 100 \ mA$





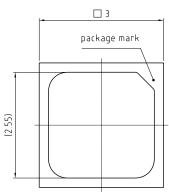
Max. Permissible Forward Current

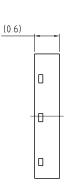
 $I_{_{F}} = f(T)$

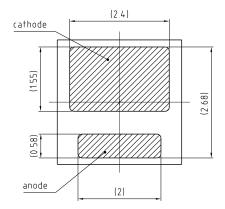




Dimensional Drawing ⁶⁾







general tolera	ance ±0.1
lead finish Ag	

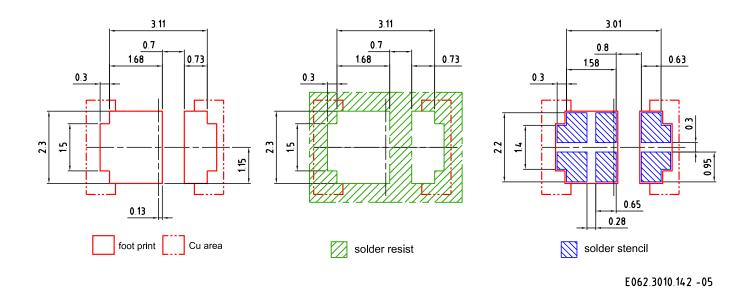
C67062-A0225-A1.-01

Further Information:

Approximate Weight:	17.7 mg
Package marking:	Cathode
ESD advice:	The device is protected by ESD device which is connected in parallel to the Chip.



Recommended Solder Pad⁶⁾

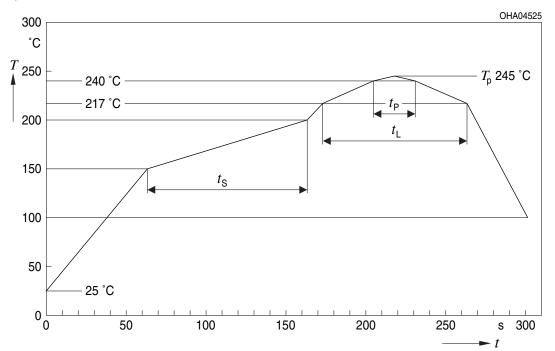


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 3 acc. to JEDEC J-STD-020E



Profile Feature Symbol		Pb	Pb-Free (SnAgCu) Assembly		
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t _s T _{smin} to T _{smax}	t _s	60	100	120	S
Ramp-up rate to peak ^{*)} T _{Smax} to T _P			2	3	K/s
Liquidus temperature	TL		217		°C
Time above liquidus temperature	t		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T_p - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

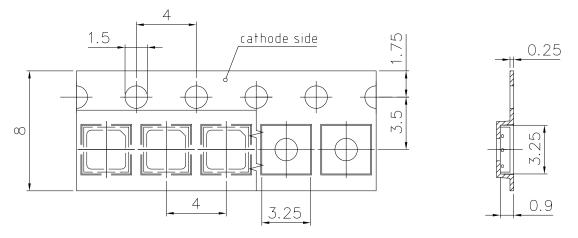
All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



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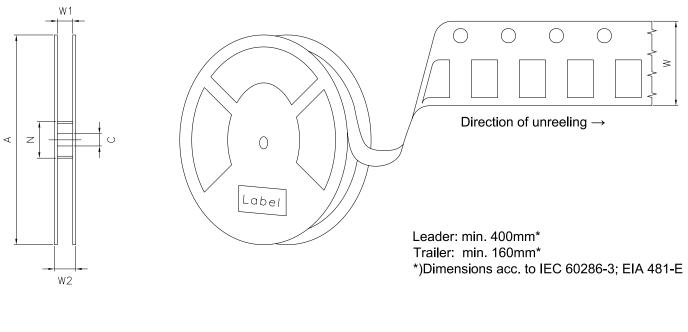
Taping ⁶⁾



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Tape and Reel ⁷⁾

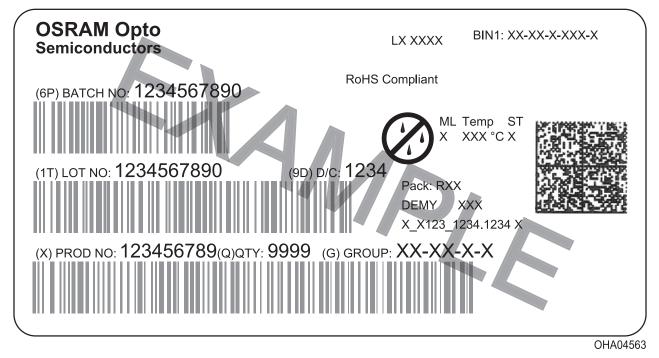


Reel Dimensions

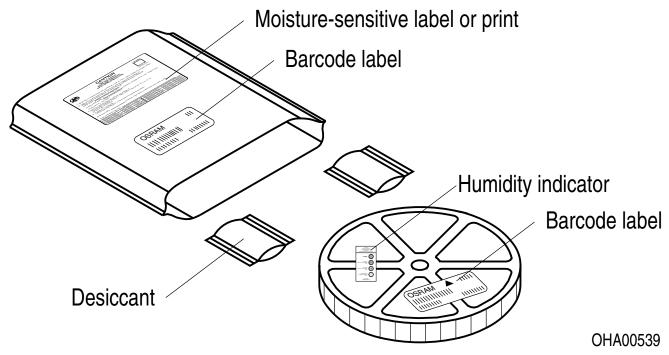
А	W	N _{min}	W ₁	$W_{2 \max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	4500



Barcode-Product-Label (BPL)



Dry Packing Process and Materials⁶⁾



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

This device is designed for specific/recommended applications only. Please consult OSRAM Opto Semiconductors Sales Staff in advance for detailed information on other non-recommended applications (e.g. automotive).

Change management for this component is aligned with the requirements of the lighting market.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



Glossary

- ¹⁾ **Brightness:** Brightness values are measured during a current pulse of typically 10 ms, with a tolerance of +/- 7%.
- Wavelength: The wavelength is measured at a current pulse of typically 10 ms, with a tolerance of ± 0.5 nm.
- ³⁾ **Forward Voltage:** The Forward voltage is measured during a current pulse duration of typically 1 ms with a tolerance of ± 0.05V.
- ⁴⁾ Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁵⁾ **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- ⁶⁾ **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ⁷⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

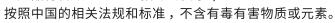


	n History		
Version	Date	Change	
1.3	2019-03-01	New Layout Recommended Solder Pad Electro - Optical Characteristics (Diagrams) Derating (Diagrams)	
1.4	2020-11-02	Further Information Taping Reel Dimensions	
1.5	2020-11-18	Applications	



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